Bill of Materials Change Description

MATERIALS	FROM	TO	REMARK
Die Attach	Able8290 Able8290 Able3230	Able8290 EN4900GC EN4900GC	Same (3x3 and 4x4mm only) Changed Changed
Wire type	Gold Wire	Gold Wire	Same
Mold Compound	Sumitomo G770	Sumitomo G700	Changed
Lead Finish	Matte Sn	Matte Sn	Same

Analog Devices Confidential Information

LFCSP 3x3 to 5x5mm
Package Outline Drawing(POD) Change Description

Body Size (mm)	Lead Count	Sawn LFCSP STATSChipPAC-China (SCC)				Sawn Type LFCSP ASE-Korea (AEK)			
		POD Spec	E-Pad Size (mm SQ.)	Lead Length (mm)	Lead Width (mm)	POD Spec	E-Pad Size (mm SQ.)	Lead Length (mm)	Lead Width (mm)
3X3	8	CP-8-12	1.60x1.60± 0.10	0.40 ± 0.10	0.25± 0.05	CP-8-11	2.34X1.60± 0.10	0.40 ± 0.10	0.25± 0.05
3X3	8	CP-8-13	1.74x1.45± 0.10	0.40 ± 0.10	0.25± 0.05	CP-8-11	2.34X1.60± 0.10	0.40 ± 0.10	0.25± 0.05
3X3	16	CP-16-27	1.50x1.50+0.15/-0.05	0.40 ± 0.10	0.25± 0.05	CP-16-22	1.60X1.60± 0.15	0.40 ± 0.10	0.23 +0.07/-0.05
4X4	20	CP-20-10	2.50x2.50± 0.15	0.40 ± 0.10	0.25± 0.05	CP-20-8	2.60X2.60+0.15/-0.25	0.40 ± 0.10	0.25 +0.05/-0.07
4X4	24	CP-24-7	2.50x2.50+0.15/-0.05	0.40 ± 0.10	0.25+0.05/-0.07	CP-24-14	2.34x2.34± 0.10	0.40 ± 0.10	0.23+0.07/-0.05
5X5	28	CP-28-6	3.30x3.30± 0.10	0.40 ± 0.10	0.25+0.05/-0.07	CP-28-10	3.14X3.14± 0.10	0.53 ± 0.05	0.25± 0.05
5X5	32	CP-32-11	3.50x3.50+0.15/-0.05	0.40 ± 0.10	0.25 +0.05/-0.07	CP-32-12	3.60X3.60+0.15/-0.05	0.40 ± 0.10	0.25+0.05/-0.07

Note) Highlighted in blue the dimensions that are changing.

Assembly Transfer to ASE Korea and Test site to STATS ChipPAC Singapore of Select LFCSP Parts

Qualification Results Summary for LFCSP at ASE Korea

QUALIFICATION RESULT			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULT**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	3 x 77	PASS
Autoclave (AC)*	JEDEC *JESD22-A102*	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	PASS
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	3 x 77	PASS

*Preconditioned per JEDEC/IPC J-STD-020